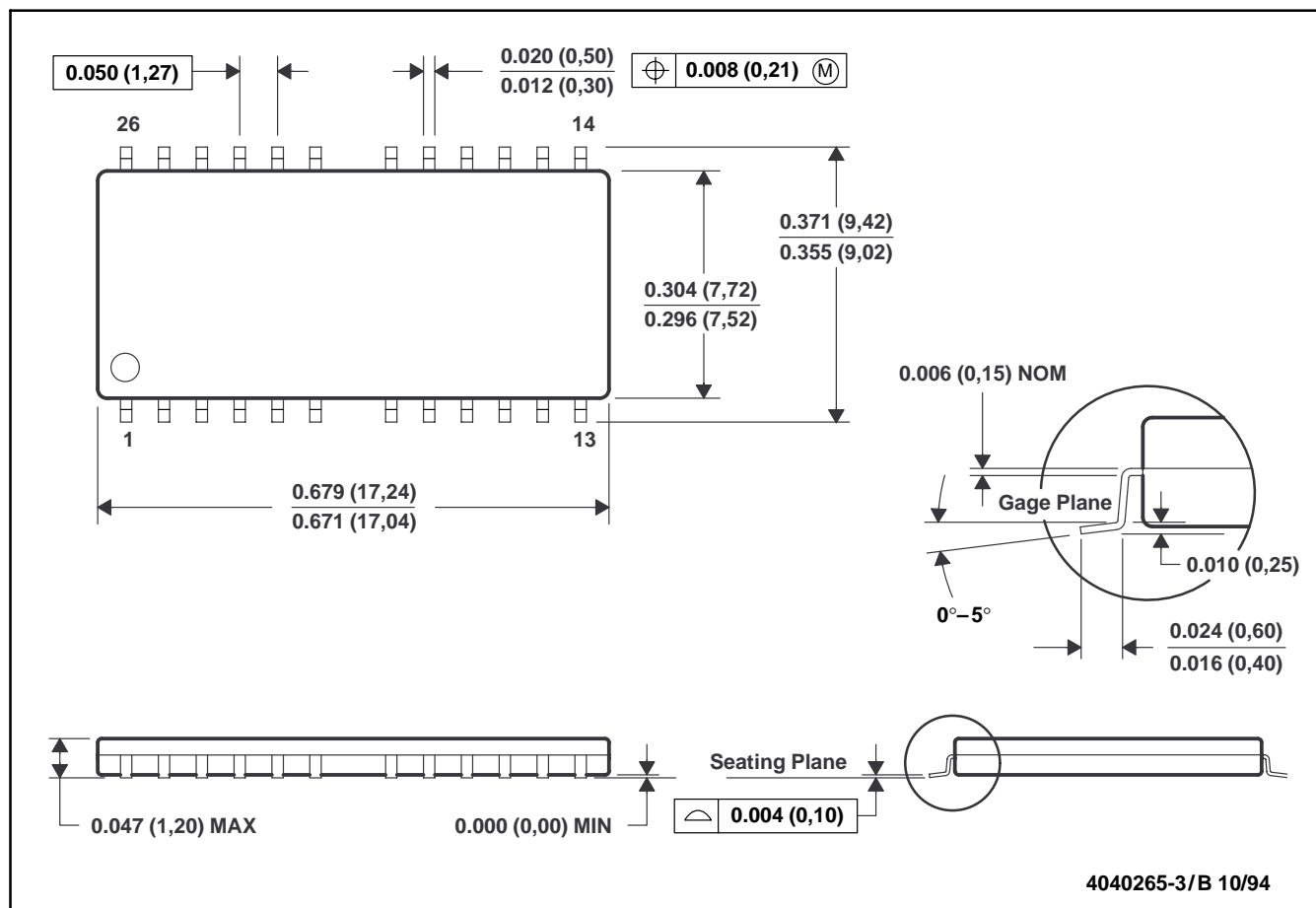


## DGA (R-PDSO-G24/26)

## PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion.



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